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1. Name of conveying party(ies):
Chen-Hui Hsieh

Additional name(s) of conveying party(ies) attached? ☐ Yes ☑ No

2. Name and address of receiving party(ies)
Name: Taiwan Semiconductor Manufacturing Company, Inc.
Internal Address:
Street Address: No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300, R.O.C.
City: State: Zip:
Additional name(s) & address(es) attached? ☐ Yes ☑ No

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3. Nature of conveyance:
☑ Assignment
☐ Merger
☐ Security Agreement
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Execution Date: December 23, 2003

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is:
A. Patent Application No.(s)
B. Patent No.(s)
Additional numbers attached? ☐ Yes ☑ No

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: David M. O'Dell
Internal Address: Haynes and Boone, LLP

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Street Address: 901 Main Street, Suite 3100
City: Dallas State: TX Zip: 75202

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41)..............$ 40.00
☑ Enclosed
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Name of Person Signing

D O'Dell
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12-30-03
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Total number of pages including cover sheet, attachments, and documents: 3

Mail documents to be recorded with required cover sheet information to:
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R63585

Cust. No. 000027683

Patent / Docket No.: 24061.157/TSMC2003-0520
Customer No. 27683

ASSIGNMENT

WHEREAS, I

Chen-Hui Hsieh of No. 136, Lane 95, Tong-Hai 1st St.
Chu-Pei City, Hsin-Chu County
Taiwan, R.O.C.

has invented certain improvements in

PROTECTION CIRCUIT LOCATED UNDER FUSE WINDOW

for which we have executed an application for Letters Patent of the United States of America, of even date herewith; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar ($1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and I hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

First Inventor Name: Chen-Hui Hsieh
Residence Address: No. 136, Lane 95, Tong-Hai 1st St.
Chu-Pei City, Hsin-Chu County
Taiwan, R.O.C.

Dated: 12/23/2003

Chen-Hui Hsieh
Inventor Signature

Dated: 12/23/2003

Witness Signature
Witness Name: Chien-Hua Huang
